

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: M.H. McKerregan et al. Date: April 9, 2009
 Application No.: 10/536,859 Examiner: N.W. Ha
 Filing Date: June 26, 2006 Group Art Unit: 2814
 Title: PACKAGE HAVING EXPOSED INTEGRATED
 CIRCUIT DEVICE

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Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

REQUEST FOR CONSIDERATION OF FOREIGN PATENT DOCUMENT

Sir:

Further to the Information Disclosure Statement filed in this application on March 16, 2009, the applicants respectfully request consideration of Taiwan patent document TW 501246, which was submitted on March 25, 2009.

This document was cited in an office action in a counterpart foreign application, and listed on the Information Disclosure Statement (form PTO/SB/08a) filed on March 16, 2009. A copy of the reference is attached for the Examiner's convenience.

CERTIFICATE OF MAILING OR TRANSMISSION (37 C.F.R. § 1.8(a))

I hereby certify that this correspondence (along with any paper referred to as being attached or enclosed) is being:

- ☐ deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.
- ☐ transmitted by facsimile on the date shown below to the United States Patent and Trademark Office at (571) 273-8300.
- ☒ transmitted via the electronic filing system of the United States Patent and Trademark Office on the date shown below and in accordance with 37 C.F.R. § 1.6(a)(4).

April 9, 2009

Signed: _____

Jay H. Anderson

As previously noted, this patent document is not in the English language. A concise explanation of the relevance of this reference has been forwarded to the undersigned attorney by English-speaking attorneys in Taiwan involved with the counterpart application. These attorneys are believed to be the persons designated in 37 C.F.R. § 1.56(c) most knowledgeable about the content of the reference. Their explanation is as follows:

The reference describes a process including providing a semiconductor wafer, wherein a plurality of chips are formed thereon and a plurality of bonding pads are formed on the central area of the chip; cutting adjacent chips so as to form a recess on the edge of a second surface and a recess on the edge of a first surface of each chip; cutting the wafer so as to form a plurality of single chips; forming a solder on each bonding pad; and encapsulating the chip and the recesses with resin.

In particular, with regard to FIG. 25 of the reference (which appears on page 46 of the attached copy), the reference describes a process with these steps: Providing a semiconductor wafer 22, wherein a plurality of chips 12 are formed thereon and a plurality of bonding pads 14 are formed on the central area of the chip 12; cutting the adjacent chips so as to form a recess 18 on the edge of a second surface and a recess 48 on the edge of a first surface of each chip 12; cutting the wafer 22 so as to form a plurality of single chips 12; forming a solder 30 on each bonding pad 14; and encapsulating the chip 12 and the recesses 18 and 48 with resin.

The applicants wish to point out that the package formed by the above-described steps in the reference (and shown on page 46 of the reference) is clearly distinct from the device package of allowed independent claim 1. For example, the above-described process does not form a plurality of conductive leads, as recited in the claim. It follows that this process does not include partially encapsulating the conductive leads with a resin, as also recited in claim 1. Furthermore, the process does not result in a package having a peripheral region of an electrically active surface of a device where metallized bumps are disposed, as also recited in claim 1.

It is respectfully submitted that all requirements of 37 C.F.R. § 1.98 have been met. Accordingly, the applicants respectfully request that this reference be made of record in the present application, without withdrawing the application from issue.

No fee is believed to be due. The Commissioner is nevertheless authorized to charge any required fees to Deposit Account No. 23-1665.

The applicants' undersigned attorney may be reached by telephone at 212-551-2625. All correspondence should continue to be directed to the address given below, which is the address associated with Customer Number 27267.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Jay H. Anderson", with a long horizontal flourish extending to the right.

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